

Data Sheet Issue:- 1

Phase Control Thyristor For Rotating Applications

Types N1479NC24R to N1479NC30R

Absolute Maximum Ratings

| | VOLTAGE RATINGS | MAXIMUM LIMITS | UNITS |
|------------------|---|-------------------|-------|
| V _{DRM} | Repetitive peak off-state voltage, (note 1) | 2400-3000 | V |
| V _{DSM} | Non-repetitive peak off-state voltage, (note 1) | 2400-3000 | V |
| V _{RRM} | Repetitive peak reverse voltage, (note 1) | 2400-3000 | V |
| V _{RSM} | Non-repetitive peak reverse voltage, (note 1) | 2500-3100 | V |

| | OTHER RATINGS | MAXIMUM LIMITS | UNITS |
|-----------------------|--|----------------------|------------------|
| I _{T(AV)} | Mean on-state current. T _{sink} =55°C, (note 2) | 1436 | А |
| I _{T(AV)} | Mean on-state current. T _{sink} =85°C, (note 2) | 989 | А |
| I _{T(AV)} | Mean on-state current. T _{sink} =85°C, (note 3) | 602 | А |
| I _{T(RMS)} | Nominal RMS on-state current. T _{sink} =25°C, (note 2) | 2830 | А |
| I _{T(d.c.)} | D.C. on-state current. T _{sink} =25°C, (note 4) | 2466 | А |
| I _{TSM} | Peak non-repetitive surge t_p =10ms, V_{RM} =0.6 V_{RRM} , (note 5) | 21 | kA |
| I _{TSM2} | Peak non-repetitive surge $t_p=10ms$, $V_{RM} \le 10V$, (note 5) | 23 | kA |
| l ² t | $I^2 t$ capacity for fusing $t_p = 10 ms, V_{RM} = 0.6 V_{RRM}$, (note 5) | 2.21×10 ⁶ | A ² s |
| l ² t | $I^{2}t$ capacity for fusing t_{p} =10ms, V_{RM} ≤10V, (note 5) | 2.65×10 ⁶ | A ² s |
| (-1; /-14) | Maximum rate of rise of on-state current (repetitive), (Note 6) | 200 | A/µs |
| (di/dt) _{cr} | Maximum rate of rise of on-state current (non-repetitive), (Note 6) | 400 | A/µs |
| V _{RGM} | Peak reverse gate voltage | 5 | V |
| P _{G(AV)} | Mean forward gate power | 4 | W |
| P _{GM} | Peak forward gate power | 30 | W |
| V_{GD} | Non-trigger gate voltage, (Note 7) | 0.25 | V |
| T _{HS} | Operating temperature range | -40 to +125 | °C |
| T _{stg} | Storage temperature range | -40 to +150 | °C |

Notes: -

- 1) De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125°C T_j initial.
- 6) $V_D=67\% V_{DRM}$, $I_{TM}=3000A$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.

7) Rated V_{DRM}.

Characteristics

| | PARAMETER | MIN. | TYP. | MAX. | TEST CONDITIONS (Note 1) | UNITS |
|-----------------------|--|------|------|-------|---|------------------|
| V _{TM} | Maximum peak on-state voltage | - | - | 1.9 | I _{TM} =2550A | V |
| V _{T0} | Threshold voltage | - | - | 1.0 | | V |
| r⊤ | Slope resistance | - | - | 0.342 | | mΩ |
| (dv/dt) _{cr} | Critical rate of rise of off-state voltage | 1000 | - | - | V_{D} =80% V_{DRM} , linear ramp | V/µs |
| I _{DRM} | Peak off-state current | - | - | 100 | Rated V _{DRM} | mA |
| I _{RRM} | Peak reverse current | - | - | 100 | Rated V _{RRM} | mA |
| V _{GT} | Gate trigger voltage | - | - | 3.0 | | V |
| I _{GT} | Gate trigger current | - | - | 300 | T _j =25°C, V _D =10V, I _T =2A | mA |
| I _H | Holding current | - | - | 1000 | T _j =25°C | mA |
| t _{gd} | Gate controlled turn-on delay time | - | 0.6 | 1.5 | V _D =80%V _{DRM} , I _{TM} =2000A, di/dt=10A/µs, | |
| t _{gt} | Turn-on time | - | 1.2 | 2.5 | I _{FG} =2A, t _r =0.5μs, T _j =25°C | μs |
| Q _{rr} | Recovered Charge | - | 3600 | - | | μC |
| Q _{ra} | Recovered Charge, 50% chord | - | 2700 | 2900 | I _{TM} =1000A, t _p =1ms, di/dt=10A/μs, V _r =50V | μC |
| l _{rm} | Reverse recovery current | - | 140 | - | $t_{\rm TM} = 1000$ A, $t_{\rm p} = 111$ S, $dt/dt = 10$ A/µS, $v_{\rm f} = 50$ V | А |
| t _{rr} | Reverse recovery time, 50% chord | - | 40 | - | | μs |
| t _q | Turn-off time | - | 390 | 500 | I _{TM} =1000A, t _p =1ms, di/dt=10A/µs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=20V/µs | - µs |
| | | - | 560 | 700 | I_{TM} =1000A, t _p =1ms, di/dt=10A/µs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=200V/µs | |
| R_{thJK} | Thermal resistance, junction to heatsink | - | - | 0.022 | Double side cooled | K/W |
| | | - | - | 0.044 | Single side cooled | K/W |
| F | Mounting force | 19 | - | 26 | | kN |
| а | Acceleration | - | - | 620 | (note 2) | m/s ² |
| W _t | Weight | - | 510 | - | | g |

Notes: -

1) Unless otherwise indicated $T_j=125$ °C. 2) Device suitable for a maximum acceleration of 620m/s² in the Y axis and clamped with the anode facing the centre of rotation.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

| Voltage Grade | V _{DRM} V _{DSM} V _{RRM} V | V _{RSM} V | V _D V _R DC V |
|---------------|---|-----------------------|---------------------------------------|
| 24 | 2400 | 2500 | 1450 |
| 26 | 2600 | 2700 | 1550 |
| 28 | 2800 | 2900 | 1650 |
| 30 | 3000 | 3100 | 1750 |

2.0 Extension of Voltage Grades

This report is applicable to other and higher voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

<u>4.0 Repetitive dv/dt</u> Standard dv/dt is 1000V/µs.

5.0 Snubber Components

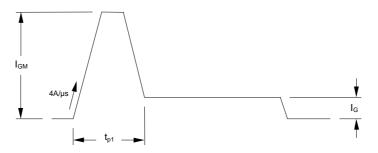
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 600A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 300A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff \cdot r_{T}} \text{ and:} \qquad \begin{aligned} W_{AV} = \frac{\Delta T}{R_{th}} \\ \Delta T = T_{j\max} - T_{Hs} \end{aligned}$$

Where V_{T0} =1.0V, r_T=0.342m Ω ,

 R_{th} = Supplementary thermal impedance, see table below.

ff = Form factor, see table below.

| Supplementary Thermal Impedance | | | | | | | |
|---------------------------------|--------|--------|--------|--------|--------|--------|--------|
| Conduction Angle | 30° | 60° | 90° | 120° | 180° | 270° | d.c. |
| Square wave Double Side Cooled | 0.0312 | 0.0285 | 0.0267 | 0.0255 | 0.0240 | 0.0228 | 0.0220 |
| Square wave Single Side Cooled | 0.0543 | 0.0513 | 0.0496 | 0.0484 | 0.0469 | 0.0455 | 0.0440 |
| Sine wave Double Side Cooled | 0.0256 | 0.0246 | 0.0239 | 0.0233 | 0.022 | | |
| Sine wave Single Side Cooled | 0.0509 | 0.0482 | 0.0471 | 0.0463 | 0.044 | | ······ |

| Form Factors | | | | | | | |
|------------------|------|------|------|------|------|------|------|
| Conduction Angle | 30° | 60° | 90° | 120° | 180° | 270° | d.c. |
| Square wave | 3.46 | 2.45 | 2 | 1.73 | 1.41 | 1.15 | 1 |
| Sine wave | 3.98 | 2.78 | 2.22 | 1.88 | 1.57 | | |

8.2 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- (i) the well established V_{T0} and r_T tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

| 25°C Coefficients | | 125°C Coefficients | | |
|-------------------|---------------------------|--------------------|--------------------------|--|
| Α | 1.136175 | Α | 2.01023758 | |
| В | -0.03504027 | В | -0.2896884 | |
| С | 2.065692×10 ⁻⁴ | С | 8.03792×10 ⁻⁵ | |
| D | 8.168895×10 ⁻³ | D | 0.03875571 | |

8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t = Duration of heating pulse in seconds.
- $r_{t} =$ Thermal resistance at time t.
- r_p = Amplitude of p_{th} term.

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 τ_p = Time Constant of r_{th} term.

| D.C. Double Side Cooled | | | | | | |
|-------------------------|---------------------------|---------------------------|---------------------------|---------------------------|--|--|
| Term 1 2 4 5 | | | | | | |
| r _p | 3.424745×10 ⁻³ | 1.745273×10 ⁻³ | 8.532017×10 ⁻⁴ | 3.457329×10 ⁻⁴ | | |
| τρ | 1.125391 | 0.1878348 | 0.02788979 | 8.430889×10 ⁻³ | | |

| D.C. Single Side Cooled | | | | | | | |
|-------------------------|---------------------------|---------------------------|---------------------------|--------------------------|--|--|--|
| Term | Term 1 2 5 6 | | | | | | |
| r _p | 8.375269×10 ⁻³ | 2.518437×10 ⁻³ | 1.193758×10 ⁻³ | 7.45432×10 ⁻⁴ | | | |
| $	au_{p}$ | 8.929845 | 0.4711304 | 0.08221244 | 0.01221961 | | | |

9.0 Reverse recovery ratings

(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1.

(ii) Q_{rr} is based on a 150µs integration time.

i.e.
$$Q_{rr} = \int_{0}^{150\,\mu s} i_{rr}.dt$$

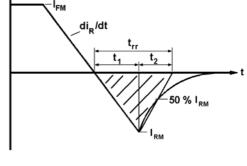


Fig. 1

(iii) $K \ Factor = \frac{t1}{t2}$

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<u>Curves</u>

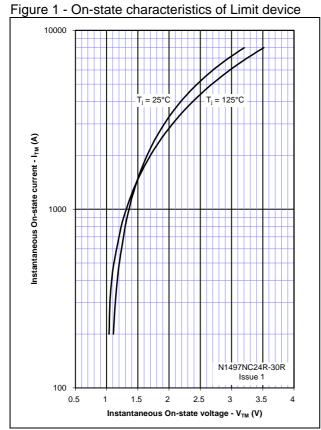
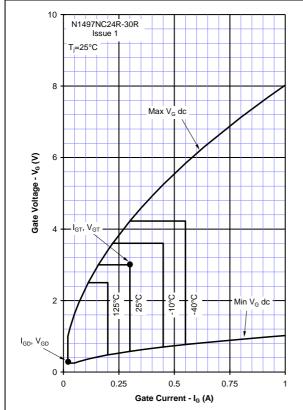


Figure 3 - Gate Characteristics - Trigger Limits



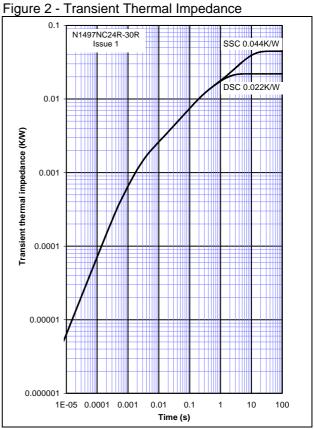
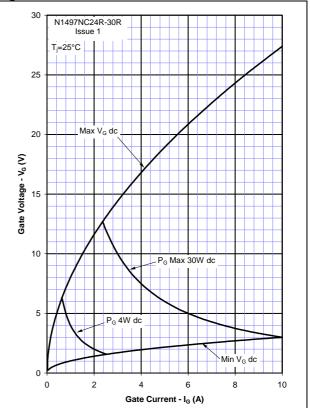


Figure 4 - Gate Characteristics - Power Curves





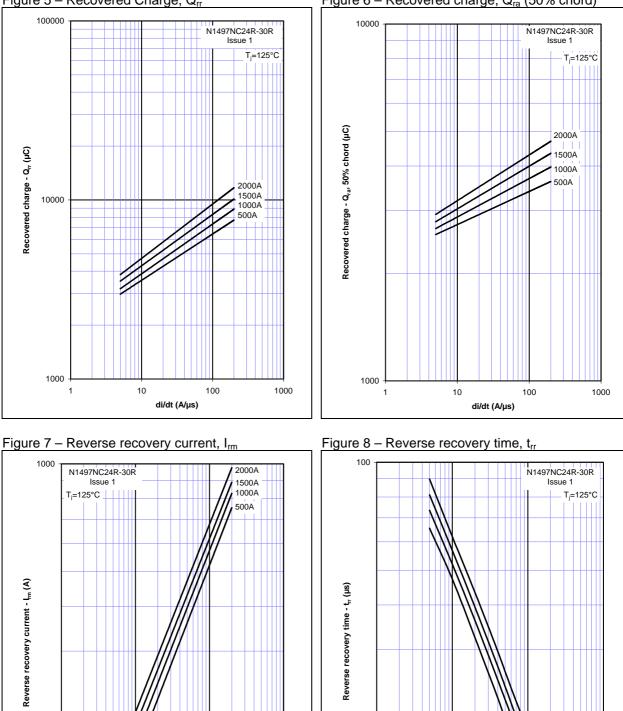


Figure 5 – Recovered Charge, Q_{rr}

Figure 6 – Recovered charge, Q_{ra} (50% chord)

10

di/dt (A/µs)

100

100

1

1000

10

1

10

di/dt (A/µs)

1000

2000A 1500A 1000A 500A

100



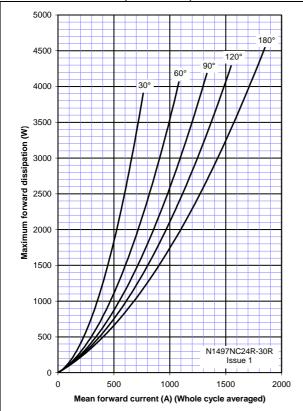


Figure 9 - On-state current vs. Power dissipation -Double Side Cooled (Sine wave)

Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

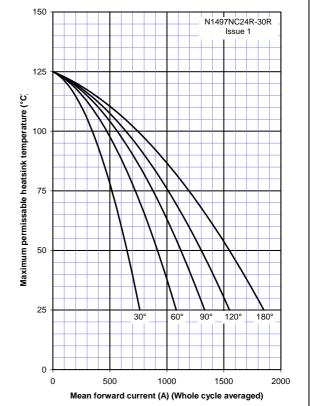
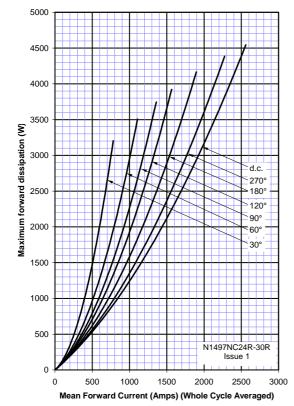
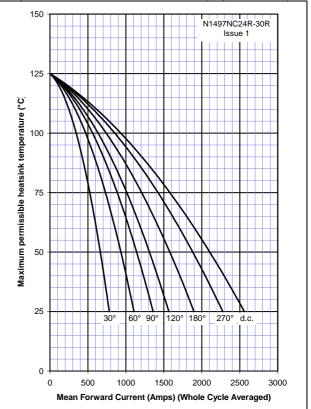


Figure 11 – On-state current vs. Power dissipation – Figure 12 – On-state current vs. Heatsink Double Side Cooled (Square wave)



temperature - Double Side Cooled (Square wave)



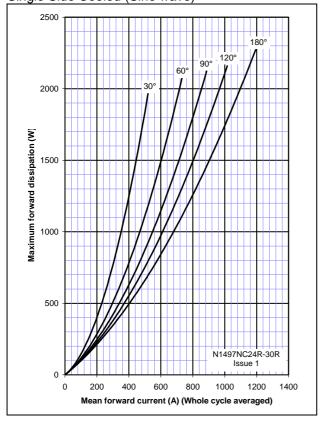


Figure 13 – On-state current vs. Power dissipation – Figure 14 – On-state current vs. Heatsink Single Side Cooled (Sine wave)

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temperature - Single Side Cooled (Sine wave)

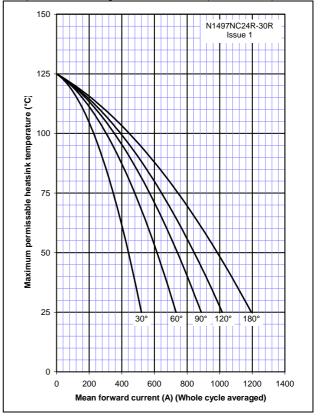
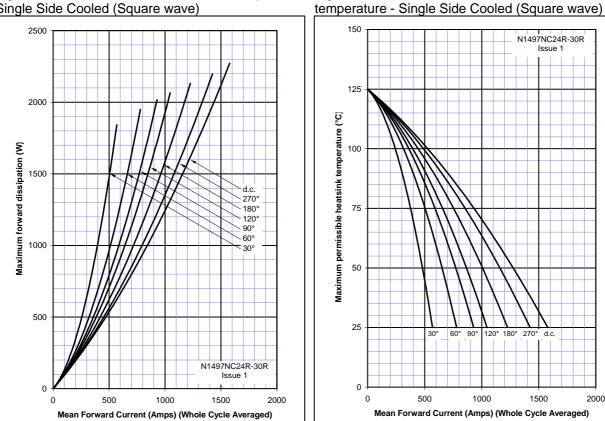


Figure 15 – On-state current vs. Power dissipation – Figure 16 – On-state current vs. Heatsink Single Side Cooled (Square wave)



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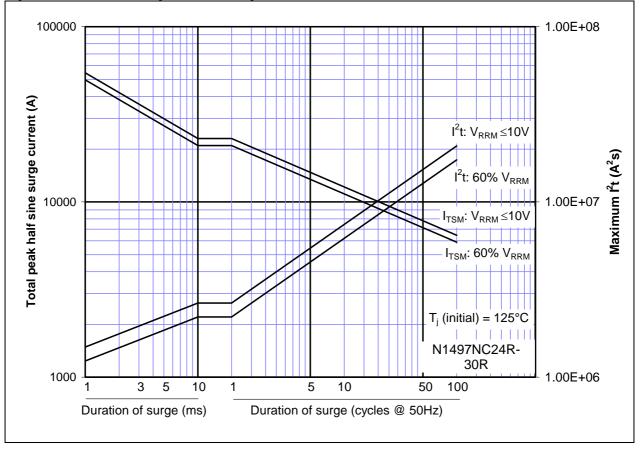


Figure 17 – Maximum surge and I²t Ratings



Outline Drawing & Ordering Information

